ON Semiconductor

Product Bulletin

Document # : PB20643XA
Issue Date: 21 May 2015

Title of Change:	Change of Carrier Tape Design.
Effective Date:	Effective Immediately
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Type of notification:	ON Semiconductor considers this change approved unless specific conditions of acceptance are provided in writing. To do so, contact <PCN.Support@onsemi.com>.

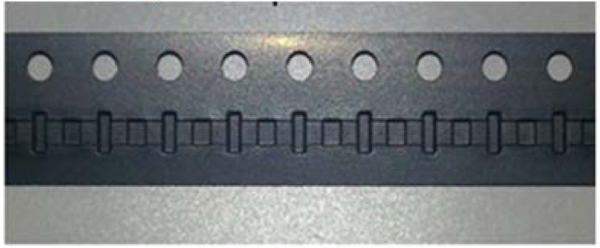
Change category(s):
☐ Wafer Fab Change
☐ Assembly Change
☐ Test Change
☐ Manufacturing Site Change/Addition
☐ Manufacturing Process Change
☐ Material Change
☐ Product specific change
☐ Datasheet/Product Doc change
☒ Shipping/Packaging/Marking
☐ Other: ________________________

Sites Affected: ☐ All site(s) ☐ not applicable ☒ ON Semiconductor site(s) : ☐ External Foundry/Subcon site(s):	Site 1 ON Tarlac City, Philippines	Site 2

Description and Purpose:

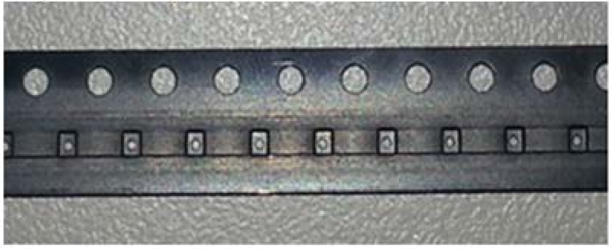
- Change design of CARR(WLP0.9X1.1X650) from without pocket hole to with pocket hole
- Standardize carrier tape design by removing rectangular pocket between device pocket

Current Design



- Without pocket hole
- With rectangular pocket in between device pocket

Proposed Design



- With 0.35 mm pocket hole
- Rectangular pocket is removed

List of affected Standard Parts:

LE24L042CS-B-TFM-H